

DLA Land and Maritime - VQ
Supplemental Information Sheet for Electronic QML-31032

Date: 6/24/2013

Specification Details:

Specification: MIL-PRF-31032
Title: Printed Circuit Board/Printed Wiring Board
Federal Supply Class (FSC): 5998
Conventional: No
Specification contains quality assurance program: Yes
MIL-STD-790 Established Reliability & High Reliability: No
MIL-STD-690 Failure Rate Sampling Plans & Procedures: No
Weibull Graded: Yes
Specification contains space level reliability requirements: No
Specification allows test optimization: Yes

Contact Information:

Office of Primary Involvement: Electronic Devices Branch, DLA Land and Maritime - VQE
Primary Qualifying Activity Contact: 614-692-0627, e-mail: vqe.ls@dla.mil

Notes:

If a manufacturer desires to have test data considered for qualification, it must be certified and meet all qualification test requirements of MIL-PRF-31032 and the applicable associated specification.

The listing of printed board manufacturing lines in the QML applies only to printed boards produced in the plant(s) specified herein. Therefore, only those printed boards that have been manufactured and tested on the certified/qualified lines listed herein can be supplied as QML printed boards.

The DLA Land and Maritime - VQE contacts for QML companies can be located in the file "31032 main points-of-contact" at website: http://www.dsccl.dla.mil/offices/sourcing_and_qualification/offices.asp?section=VQE

QML is a definition of a manufacturer's verified capabilities. Manufacturers may use the add-on qualification process to qualify capabilities that are not currently listed on the QML. The user is encouraged to contact the manufacturer or Qualifying Activity to make arrangements for QML availability.

The following abbreviations are used in this listing:

Ag: Silver
Au: Gold
CAGE: Commercial and Government Entity (Code)
Cu: Copper
ENIG: Electroless Nickel Immersion Gold
HASL: Hot Air Solder Level
ImmAg: Immersion Silver
IR: Infrared
LPI: Liquid Photoimageable
MIX: Mix of SMT and THM
Ni: Nickel
OSP: Organic Surface Protection
Pb: Lead
Pd: Palladium
PTH: Plated Thru Hole
SMOBC: Solder Mask Over Bare Copper
SMT: Surface-Mount Technology
Sn: Tin
THM: Through-Hole Mounting

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: AC Universal Circuits LLC 8860 Zachary Lane North, Maple Grove, MN, 55369-4524 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 45032 Phone: 763-315-1702 Fax: 763-425-0999 EMail: sbialka@universalcircuits.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-10-019530, VQE-10-020323, VQE-12-024534
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 18
 Max. Board Thickness: .125"
 Min. Hole Size: .008" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 8.88:1 Through-Hole
 Min. Conductor Width/Space: .0032"/.0032"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Carbon-based
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL, ImmAg
 Additional Fab Capabilities: Foil Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-10-019530, VQE-10-020323, VQE-12-024534
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; Woven Glass Reinforced, Hydrocarbon Resin with Ceramic Fill
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 18
 Max. Board Thickness: .18"
 Min. Hole Size: .021" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 8.57:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Carbon-based
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL, ImmAg
 Additional Fab Capabilities: Blind Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-11-021326, VQE-12-024534
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 8
 Max. Board Thickness: .062"
 Min. Hole Size: .0138" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 4.5:1 Through-Hole
 Min. Conductor Width/Space: .007"/.006"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Carbon-based
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL, ImmAg
 Additional Fab Capabilities: Foil Lamination

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MANUFACTURER INFORMATION: Accurate Circuit Engineering 3019 S. Kilson Drive, Santa Ana, CA, 92707 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 0MNN9 Phone: 714-546-2162 Fax: 714-433-7418 EMail: quality@ace-pcb.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-06-012150, VQE-07-012577, VQE-09-018384, VQE-10-020411, VQE-11-022279
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 20" x 26"
 Max. Number of Layers: 24
 Max. Board Thickness: .22"
 Min. Hole Size: .008" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 11:1 Through-Hole
 Min. Conductor Width/Space: .003"/.003"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL, ImmAg
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Advanced Circuits - Tempe Division 229 S. Clark Drive, Tempe, AZ, 85281-3073</p>		<p>CAGE Code: 6RJS1 Phone: 480-966-5894 Fax: 480-966-5896 EMail: tempesales@4pcb.com</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-12-024291, VQE-12-024631, VQE-12-025042, VQE-13-025402, VQE-13-025881
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 24
 Max. Board Thickness: .125"
 Min. Hole Size: .004" Laser Abated Plated Hole Size Before Plating, .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 12.5:1 Through-Hole
 Min. Conductor Width/Space: .004"/.0047"
 Hole Preparation: Permanganate Desmear, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL, ImmAg
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-12-024291, VQE-12-024631, VQE-12-025042, VQE-13-025402, VQE-13-025881
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 24
 Max. Board Thickness: .125"
 Min. Hole Size: .004" Laser Abated Plated Hole Size Before Plating, .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 12.5:1 Through-Hole
 Min. Conductor Width/Space: .004"/.0047"
 Hole Preparation: Permanganate Desmear, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL, ImmAg
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Airborn Flexible Circuits, Inc. 11 Dohme Avenue, Toronto, Ontario Canada M4B 1Y7	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 38661 Phone: 416-285-3825 Fax: 416-752-6719 E-Mail: pialisp@airbornflex.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-04-005354, VQE-08-015729
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Polyimide with Acrylic Adhesive
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 7
 Max. Board Thickness: " Not Specified
 Aspect Ratio: 3:1 Through-Hole
 Min. Conductor Width/Space: .007"/.007"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Direct Metalization
 Copper Plating: Direct Current Plate
 Solder Resist: Dry Film, Liquid Photoimageable, Silk Screen
 Finish System: HASL
 Additional Fab Capabilities: Copper Core, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-04-005354, VQE-08-015729
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Flex Base Material: Copper Clad Adhesiveless Polyimide
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 12
 Max. Board Thickness: .094"
 Min. Hole Size: .008" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 12:1 Through-Hole
 Min. Conductor Width/Space: .006"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Direct Metalization
 Copper Plating: Direct Current Plate
 Solder Resist: Dry Film, Liquid Photoimageable, Silk Screen
 Finish System: HASL
 Additional Fab Capabilities: Copper Core, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

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MANUFACTURER INFORMATION: American Standard Circuits 475 Industrial Drive, West Chicago, IL, 60185 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 4AA34 Phone: 603-639-5444 Fax: 603-293-1240 E-Mail: sales@asc-i.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-08-015934, VQE-11-021830, VQE-11-023138, VQE-13-025323, VQE-13-025791, VQE-13-025834
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 14
 Max. Board Thickness: .09" (for /1, Type 3 - Multilayer), .125" (for /2, Type /2 - Double-sided only)
 Min. Hole Size: .009" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 7:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL, ImmAg
 Additional Fab Capabilities: Blind Vias, Foil Lamination

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-11-022358
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 10
 Max. Board Thickness: .125"
 Min. Hole Size: .02" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 5:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL, ImmAg

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Amphenol Printed Circuits 91 Northeastern Boulevard, Nashua, NH, 03062 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 57034 Phone: 603-879-3268 Fax: 603-879-2818 EMail: denise.chevalier@amphenol-tcs.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE 10-020582, VQE-06-010054, VQE-09-017008, VQE-12-023765, VQE-97-000649
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 24" x 42"
 Max. Number of Layers: 33
 Max. Board Thickness: .25"
 Min. Hole Size: .008" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: .6:1 Microvia, 11:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Permanganate Etchback, Permanganate Etchback, Plasma Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Pulse Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable, Silk Screen
 Finish System: ENIG, Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Foil Lamination, Press Fit Mounting, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE 10-020582, VQE-06-010054, VQE-09-017008, VQE-12-023765, VQE-97-000649
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 30" x 36"
 Max. Number of Layers: 28
 Max. Board Thickness: .18"
 Min. Hole Size: .0158" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 11:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Pulse Plate
 Hole Fill/Via Plug: Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable, Silk Screen
 Finish System: ENIG, Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Foil Lamination, Press Fit Mounting
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE 10-020582, VQE-06-010054, VQE-09-017008, VQE-12-023765
 Composition: H - Homogenous thermoplastic base material printed boards, M - Mixed based material printed boards
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; Woven Glass Reinforced, Hydrocarbon Resin with Ceramic Fill
 Max. Panel Size: 21" x 24"
 Max. Number of Layers: 12
 Max. Board Thickness: .101"
 Min. Hole Size: .033" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: .5:1 Microvia, 3:1 Through-Hole
 Min. Conductor Width/Space: .004"/.003"
 Hole Preparation: Permanganate Desmear, Plasma Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Pulse Plate
 Hole Fill/Via Plug: Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable, Silk Screen
 Finish System: ENIG, Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Foil Lamination, Press Fit Mounting, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Amphenol Printed Circuits 91 Northeastern Boulevard, Nashua, NH, 03062 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 57034 Phone: 603-879-3268 Fax: 603-879-2818 EMail: denise.chevalier@amphenol-tcs.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-10-019533, VQE-12-023765
 Flex Base Material: Copper Clad Polyimide with Acrylic Adhesive
 Max. Panel Size: 24" x 36"
 Max. Number of Layers: 4 (types 1, 2, and 3 only)
 Max. Board Thickness: .031"
 Min. Hole Size: .0145"
 Aspect Ratio: .7:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Palladium-based
 Copper Plating: Direct Current Plate, Pulse Plate
 Finish System: HASL, Hot Oil Reflow of Plated Sn/Pb
 Flex Usage: Use A (Flex During Installation)

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-10-019533, VQE-12-023765
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Adhesiveless Polyimide
 Max. Panel Size: 24" x 49"
 Max. Number of Layers: 22
 Max. Board Thickness: .14"
 Min. Hole Size: .12" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 7.75:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper, Palladium-based
 Copper Plating: Direct Current Plate, Pulse Plate
 Finish System: Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Foil Lamination, Press Fit Mounting, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended
 Flex Usage: Use A (Flex During Installation)

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Calumet Electronics Corp. 25830 Depot Street, Calumet, MI, 49913-1985 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 65337 Phone: 906-337-1305 Fax: 906-337-5359 EMail: quality@calumetelectronics.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE 12 023734, VQE-03-4657, VQE-04-6280
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 21" x 24"
 Max. Number of Layers: 10
 Max. Board Thickness: .125"
 Min. Hole Size: .016" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 8:1 Through-Hole
 Min. Conductor Width/Space: .004"/.003"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL
 Additional Fab Capabilities: Press Fit Mounting

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE 12 023734, VQE-03-4657, VQE-04-6280, VQE-13-026419
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 21" x 24"
 Max. Number of Layers: 14
 Max. Board Thickness: .125"
 Min. Hole Size: .016" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 8:1 Through-Hole
 Min. Conductor Width/Space: .004"/.003"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Cirexx International, Inc. 791 Nuttman Street, Santa Clara, CA, 95054 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 4MEG7 Phone: 408-988-3980 Fax: 408-988-4534 E-Mail: dangulo@cirexxintl.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1
 Qualification Letters: VQ(VQE-08-016602)
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 22
 Max. Board Thickness: .125"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 12.5:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL
 Additional Fab Capabilities: Foil Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1
 Qualification Letters: VQ(VQE-08-016602)
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 22
 Max. Board Thickness: .125"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 12.5:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL
 Additional Fab Capabilities: Foil Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-07-014176)
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 2
 Max. Board Thickness: .1"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 10:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni/Au, HASL

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MANUFACTURER INFORMATION: Cirexx International, Inc. 791 Nuttman Street, Santa Clara, CA, 95054 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 4MEG7 Phone: 408-988-3980 Fax: 408-988-4534 E-Mail: dangulo@cirexxintl.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3
 Qualification Letters: VQ(VQE-07-014176)
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Flex Base Material: Copper Clad Adhesiveless Polyimide
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 2
 Max. Board Thickness: .1"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 10:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni/Au, HASL
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3
 Qualification Letters: VQ(VQE-07-014176)
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Flex Base Material: Copper Clad Polyimide with Acrylic Adhesive
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 2
 Max. Board Thickness: .1"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 10:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni/Au, HASL
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/4
 Qualification Letters: VQ(VQE-08-016602)
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Adhesiveless Polyimide
 Max. Panel Size: 12" x 18", 18" x 24"
 Max. Number of Layers: 20
 Max. Board Thickness: .125"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 10:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL
 Additional Fab Capabilities: Foil Lamination
 Controlled Impedance: Differential, Single-Ended
 Flex Usage: Use A (Flex During Installation)

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Cirex International, Inc. 791 Nuttman Street, Santa Clara, CA, 95054 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 4MEG7 Phone: 408-988-3980 Fax: 408-988-4534 E-Mail: dangulo@cirexintl.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/4
 Qualification Letters: VQ(VQE-08-016602)
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Polyimide with Acrylic Adhesive
 Max. Panel Size: 12" x 18", 18" x 24"
 Max. Number of Layers: 20
 Max. Board Thickness: .125"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 10:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL
 Additional Fab Capabilities: Foil Lamination
 Controlled Impedance: Differential, Single-Ended
 Flex Usage: Use A (Flex During Installation)

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Colonial Circuits, Inc. 1026 Warrenton Road, Fredericksburg, VA, 22406-6200 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 6T499 Phone: 540-753-5511, x125 Fax: 540-752-2109 EMail: quality@colonialcircuits.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-04-6002
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 14
 Max. Board Thickness: .088"
 Min. Hole Size: .021" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 4.2:1 Through-Hole
 Min. Conductor Width/Space: .006"/.005"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: HASL

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-04-6002
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 12
 Max. Board Thickness: .127"
 Min. Hole Size: .015"
 Aspect Ratio: 8.5:1 Through-Hole
 Min. Conductor Width/Space: .008"/.005"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: HASL

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/5, MIL-PRF-31032/6
 Qualification Letters: VQE-04-6002, VQE-06-010192
 Rigid Base Material: Woven Glass Reinforced, Hydrocarbon Resin with Ceramic Fill
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 8
 Max. Board Thickness: .09"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 6.2:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: HASL

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Colonial Circuits, Inc. 1026 Warrenton Road, Fredericksburg, VA, 22406-6200 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 6T499 Phone: 540-753-5511, x125 Fax: 540-752-2109 EMail: quality@colonialcircuits.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQ (VQE-10-019425)
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Adhesiveless Polyimide
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 10
 Max. Board Thickness: .093"
 Min. Hole Size: .01"
 Aspect Ratio: 8.6:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: HASL
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-04-6002
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Polyimide with Acrylic Adhesive
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 10
 Max. Board Thickness: .093"
 Min. Hole Size: .025" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 3.7:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: HASL
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/6
 Qualification Letters: VQE-04-6002
 Rigid Base Material: With or without woven or non-woven E-glass, Polytetrafluoroethylene (PTFE) resin, ceramic filler
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 2
 Max. Board Thickness: .031"
 Min. Hole Size: .02" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 1.55:1 Through-Hole
 Min. Conductor Width/Space: .025"/.01"
 Hole Preparation: Plasma Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: HASL

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Compunetics Inc. 700 Seco Rd, Monroeville, OH, 15146</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 30598 Phone: 412-858-1272 Fax: EMail: lhart@compunetics.com</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-13-026082)
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 20
 Max. Board Thickness: .099"
 Min. Hole Size: .0098" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 9.18:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear,
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL
 Controlled Impedance: Differential, Single-Ended

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Cosmotronic, Inc. 16721 Noyes Avenue, Irvine, CA, 92606 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 63695 Phone: 949-660-0740 Fax: 949-553-8371 EMail: Patricia_Alcantar@cosmotronic.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-04-006966, VQE-05-009107, VQE-06-010085, VQE-06-011248
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Board Thickness: .335"
 Min. Hole Size: .014" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 15:1 Through-Hole
 Min. Conductor Width/Space: .005"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Sequential Lamination
 Controlled Impedance: Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-04-006966, VQE-05-009107, VQE-06-010085, VQE-06-011248
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Board Thickness: .335"
 Min. Hole Size: .014" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 15:1 Through-Hole
 Min. Conductor Width/Space: .005"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Sequential Lamination
 Controlled Impedance: Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-04-006966, VQE-05-009107, VQE-06-010085
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant; GM: Glass Base, Woven, Triazine and/or Bismaleimide Modified Epoxy Resin, Flame Resistant
 Flex Base Material: Copper Clad Adhesiveless Polyimide
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 22
 Max. Board Thickness: .165"
 Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 8:1 Through-Hole
 Min. Conductor Width/Space: .006"/.008"
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Cosmotronic, Inc. 16721 Noyes Avenue, Irvine, CA, 92606 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 63695 Phone: 949-660-0740 Fax: 949-553-8371 EMail: Patricia_Alcantar@cosmotronic.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-04-006966, VQE-05-009107, VQE-06-010085
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant; GM: Glass Base, Woven, Triazine and/or Bismaleimide Modified Epoxy Resin, Flame Resistant
 Flex Base Material: Copper Clad Polyimide with Acrylic Adhesive
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 22
 Max. Board Thickness: .165"
 Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 8:1 Through-Hole
 Min. Conductor Width/Space: .006"/.008"
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/5, MIL-PRF-31032/6
 Qualification Letters: VQE-04-006966, VQE-05-009107, VQE-06-010085
 Composition: S - Homogenous thermosetting base material printed boards
 Rigid Base Material: Woven Glass Reinforced, Hydrocarbon Resin with Ceramic Fill
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 16
 Max. Board Thickness: .225"
 Min. Hole Size: .02" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 10:1 Through-Hole
 Min. Conductor Width/Space: .011"/.007"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL
 Additional Fab Capabilities: Blind Vias, Sequential Lamination

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/5, MIL-PRF-31032/6
 Qualification Letters: VQE-04-006966, VQE-05-009107, VQE-06-010085
 Composition: S - Homogenous thermosetting base material printed boards
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant; Woven Glass Reinforced, Hydrocarbon Resin with Ceramic Fill
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 16
 Max. Board Thickness: .225"
 Min. Hole Size: .02" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 10:1 Through-Hole
 Min. Conductor Width/Space: .011"/.007"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL
 Additional Fab Capabilities: Blind Vias, Sequential Lamination

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Dynamic & Proto Circuits, Inc. 869 Barton Street, Stoney Creek, Ontario Canada L8E 5G6	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 38898 Phone: 905-643-9900 Fax: 905-643-9911 EMail: dynamicinfo@dapc.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-00-0007, VQE-01-0311, VQE-03-0818, VQE-98-1143
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 16" x 18"
 Max. Number of Layers: 16
 Max. Board Thickness: .125"
 Min. Hole Size: .0135" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 9.3:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Pulse Plate
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: HASL

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-12-024252
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 16" x 18"
 Max. Number of Layers: 16
 Max. Board Thickness: .125"
 Min. Hole Size: .0135" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 9.3:1 Through-Hole
 Min. Conductor Width/Space: .025"/.025"
 Hole Preparation: Plasma Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Pulse Plate
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: HASL

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Electro Plate Circuitry, Inc. 1430 Century Drive, Carrollton, TX, 75006 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 79616 Phone: 972-466-0818 Fax: 972-466-9078 EMail: jimm@eplate.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-06-010333), VQ(VQE-06-011433), VQ(VQE-10-020352)
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 16", 18" x 24"
 Max. Number of Layers: 14
 Max. Board Thickness: .12"
 Min. Hole Size: .008" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 9.3:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-06-010333), VQ(VQE-06-011433), VQ(VQE-10-020352)
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 16", 18" x 24"
 Max. Number of Layers: 18
 Max. Board Thickness: .17"
 Min. Hole Size: .008" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 9.3:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/5, MIL-PRF-31032/6
 Qualification Letters: VQ(VQE-10-021161)
 Rigid Base Material: GT: Woven E-Glass, PTFE Resin; GX: Glass Base, Woven, Polytetrafluoroethylene Resin, Flame Resistant; GY: Glass Base, Woven, Polytetrafluoroethylene Resin, Flame Resistant, for Microwave Application; With or without woven or non-woven E-glass, Polytetrafluoroethylene (PTFE) resin, ceramic filler
 Max. Panel Size: 12" x 18", 18" x 24"
 Max. Number of Layers: 6
 Max. Board Thickness: .18"
 Min. Hole Size: .008" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 6:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Electrotek Corp. 7745 S. 10th Street, Oak Creek, WI, 53154 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 66030 Phone: 414-762-1390 Fax: 414-762-1510 E-Mail: sales@boards4u.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-06-011451), VQ(VQE-08-014513), VQ(VQE-09-018692), VQ(VQE-12-024024), VQ(VQE-12-024411)
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 18
 Max. Board Thickness: .115"
 Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 9:1 Through-Hole
 Min. Conductor Width/Space: .003"/.003"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: Carbon Ink, ENIG, Electrolytic Ni/Au, HASL, ImmAg
 Additional Fab Capabilities: Foil Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-06-011451), VQ(VQE-08-014513), VQ(VQE-09-018692), VQ(VQE-12-024024), VQ(VQE-12-024411)
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 18
 Max. Board Thickness: .115"
 Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 9:1 Through-Hole
 Min. Conductor Width/Space: .003"/.003"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: Carbon Ink, ENIG, Electrolytic Ni/Au, HASL, ImmAg
 Additional Fab Capabilities: Foil Lamination
 Controlled Impedance: Differential, Single-Ended

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Endicott Interconnect Technologies, Inc. Dept. 0069/014-3, 1093 Clark Street, Endicott, NY, 13760 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 3ECL3 Phone: 607-755-5896 Fax: 607-755-4649 E-Mail: JoseA.Rios@eitny.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-04-005311), VQ(VQE-07-012236), VQ(VQE-07-013506), VQ(VQE-08-015922), VQ(VQE-11-022684)
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 16
 Max. Board Thickness: .062"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 5:1 Through-Hole
 Min. Conductor Width/Space: .0035"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Periodic Reverse Plate, Pulse Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au
 Additional Fab Capabilities: Blind Vias, Buried Vias, Embedded Resistors, Foil Lamination, Sequential Lamination

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-04-005311), VQ(VQE-07-012236), VQ(VQE-07-013506)
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 12
 Max. Board Thickness: .084"
 Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 7:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Permanganate Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL
 Additional Fab Capabilities: Foil Lamination

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: Custom
 Qualification Letters: VQ(VQE-04-005311), VQ(VQE-07-012236), VQ(VQE-07-013506)
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 19.5" x 24"
 Max. Number of Layers: 19
 Max. Board Thickness: .153"
 Min. Hole Size: .02" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 7.6:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG
 Additional Fab Capabilities: Copper Core, Foil Lamination

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Firan Technology Group 250 Finchdene Square, Scarborough, Ontario Canada M1X 1A5	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: L2665 Phone: 416-299-4000 Fax: 416-292-4308 EMail: info@ftgcorp.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-05-009339, VQE-06-010764, VQE-06-010889
 Rigid Base Material: BI: Aramid Fabric, Nonwoven, Polyimide Resin
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 14
 Max. Board Thickness: .101"
 Min. Hole Size: .008" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 12.65:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-05-009339, VQE-06-010764, VQE-06-010889
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 20
 Max. Board Thickness: .22"
 Min. Hole Size: .0059" Laser Abated Plated Hole Size Before Plating, .0096" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 1.01:1 Microvia, 22.45:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Hole Fill/Via Plug: Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Buried Vias, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-05-009339, VQE-06-010764, VQE-06-010889
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 20
 Max. Board Thickness: .13"
 Min. Hole Size: .0059" Laser Abated Plated Hole Size Before Plating, .008" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 0.95:1 Microvia, 16.25:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Buried Vias, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Firan Technology Group 250 Finchdene Square, Scarborough, Ontario Canada M1X 1A5</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: L2665 Phone: 416-299-4000 Fax: 416-292-4308 EMail: info@ftgcorp.com</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-05-009339, VQE-06-010764, VQE-06-010889
 Rigid Base Material: GM: Glass Base, Woven, Triazine and/or Bismaleimide Modified Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 14
 Max. Board Thickness: .097"
 Min. Hole Size: .0138" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 7.03:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Global Innovations Corp. 901 Hensley Drive, Wylie, TX, 75098 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 04RV5 Phone: 214-291-1427 Fax: EMail: bnoiland@globalinnovationcorp.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-03-4341, VQE-04-5599, VQE-04-5891, VQE-05-7288
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 18
 Max. Board Thickness: .119"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 7.5:1 Through-Hole
 Min. Conductor Width/Space: .004"/.005"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: HASL
 Additional Fab Capabilities: Foil Lamination

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-04-4957, VQE-05-7288
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 12
 Max. Board Thickness: .074"
 Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 6.2:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: HASL
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/6
 Qualification Letters: VQE-07-013270, VQE-09-017797, VQE-10-020600
 Rigid Base Material: GR: Glass Base, Nonwoven, Polytetrafluoroethylene Resin, Flame Resistant
 Max. Panel Size: 9" x 16"
 Max. Number of Layers: 2
 Max. Board Thickness: .098"
 Min. Hole Size: .031" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 3.2:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Sodium Treatment
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: Electrolytic Ni / Hard Au, HASL

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Global Innovations Corp. 901 Hensley Drive, Wylie, TX, 75098 US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 04RV5 Phone: 214-291-1427 Fax: EMail: bnoiland@globalinnovationcorp.com</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/6
 Qualification Letters: VQE-11-021947
 Rigid Base Material: GY: Glass Base, Woven, Polytetrafluoroethylene Resin, Flame Resistant, for Microwave Application
 Max. Panel Size: 12" x 17"
 Max. Number of Layers: 2
 Max. Board Thickness: .031"
 Min. Hole Size: .039" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 1:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Sodium Treatment
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Finish System: Hot Oil Reflow of Plated Sn/Pb

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Gorilla Circuits 1445 Old Oakland Rd, San Jose, CA, 95112 US</p>		<p>CAGE Code: 3C7D2 Phone: 408-294-9897 Fax: 408-297-1540 EMail: info@gorillacircuits.com</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: 11-022314
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 18
 Max. Board Thickness: .18"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 18:1 Through-Hole, 1:1 Microvia
 Min. Conductor Width/Space: .004"/.005"
 Hole Preparation: Permanganate Desmear, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Pulse Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL
 Additional Fab Capabilities: Blind Vias, Buried Vias, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: 11-022314
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 18
 Max. Board Thickness: .093"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 1:1 Microvia, 9.3:1 Through-Hole
 Min. Conductor Width/Space: .004"/.005"
 Hole Preparation: Permanganate Desmear, Plasma Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Pulse Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL
 Additional Fab Capabilities: Blind Vias, Buried Vias, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Graphic Plc , Lords Meadow Industrial Estate, Down End, Crediton, Devon, EX17 IHN United Kingdom</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: U4538 Phone: 44-1363-774874 Fax: 44-1363-772265 EMail:</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
Qualification Letters: VQE-11-023205, VQE-12-025118
Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
Max. Panel Size: 12" x 18"
Max. Number of Layers: 10
Max. Board Thickness: .11" (2.79mm)
Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating
Aspect Ratio: 8.4:1 Through-Hole
Min. Conductor Width/Space: .004"/.004"
Hole Preparation: Plasma Desmear
Hole Wall Conductive Coating: Electroless Copper
Copper Plating: Pulse Plate
Solder Resist: Liquid Photoimageable
Finish System: ENIG, HASL
Additional Fab Capabilities: Foil Lamination

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
Qualification Letters: VQE-12-025119
Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
Max. Panel Size: 12" x 18"
Max. Number of Layers: 10
Max. Board Thickness: .11" (2.79mm)
Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating
Aspect Ratio: 8.4:1 Through-Hole
Min. Conductor Width/Space: .004"/.004"
Hole Preparation: Plasma Desmear, Plasma Etchback
Hole Wall Conductive Coating: Electroless Copper
Copper Plating: Pulse Plate
Solder Resist: Liquid Photoimageable
Finish System: ENIG, HASL
Additional Fab Capabilities: Foil Lamination

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Hamby Corporation 27704 Avenue Scott, Valencia, CA, 91355 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 07284 Phone: 661-257-1924 Fax: 661-257-1213 E-Mail: susharp@hambycorp.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-09-017349
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 6
 Max. Board Thickness: .035"
 Min. Hole Size: .02" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 2:1 Through-Hole
 Min. Conductor Width/Space: .009"/.009"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Finish System: Electrolytic Ni / Hard Au, HASL

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-08-14596
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Adhesiveless Polyimide
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 11
 Max. Board Thickness: .085"
 Min. Hole Size: .018" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 5:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Finish System: Electrolytic Ni / Hard Au, HASL
 Controlled Impedance: Differential, Single-Ended
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-09-017349
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 6
 Max. Board Thickness: .035"
 Min. Hole Size: .02" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 2:1 Through-Hole
 Min. Conductor Width/Space: .009"/.009"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Finish System: Electrolytic Ni / Hard Au, HASL

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Hamby Corporation 27704 Avenue Scott, Valencia, CA, 91355 US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 07284 Phone: 661-257-1924 Fax: 661-257-1213 EMail: susharp@hambycorp.com</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-08-14596
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Polyimide with Acrylic Adhesive
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 11
 Max. Board Thickness: .095"
 Min. Hole Size: .018" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 5:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Finish System: Electrolytic Ni / Hard Au, HASL
 Controlled Impedance: Differential, Single-Ended
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Hans Brockstedt GmbH Clara-Immerwahr Strasse 7, 24145 Kiel Germany	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: C4831 Phone: 0049-431-71966-0, -30 Fax: 0049-431-71966-29 E-Mail: klammer@brockstedt.de
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-03-2619, VQE-05-7480
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 9" x 13", 13" x 20", 15" x 21", 18" x 24"
 Max. Number of Layers: 12
 Max. Board Thickness: .2"
 Min. Hole Size: .004" Laser Abated Plated Hole Size Before Plating, .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 1:1 Microvia, 7:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-03-2619, VQE-05-7480,
 Composition: S - Homogenous thermosetting base material printed boards
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Adhesiveless Polyimide
 Max. Panel Size: 9" x 13", 13" x 20"
 Max. Number of Layers: 12
 Max. Board Thickness: .2"
 Min. Hole Size: .004" Laser Abated Plated Hole Size Before Plating, .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 1:1 Microvia, 7:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3
 Qualification Letters: VQE-03-2619, VQE-05-7480, VQE-13-25594
 Composition: S - Homogenous thermosetting base material printed boards
 Flex Base Material: Copper Clad Polyimide with Acrylic Adhesive
 Max. Panel Size: 9" x 13", 13" x 20"
 Max. Number of Layers: 2
 Max. Board Thickness: .01"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 1:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL, Hot Oil Reflow of Plated Sn/Pb
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Hans Brockstedt GmbH Clara-Immerwahr Strasse 7, 24145 Kiel Germany	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: C4831 Phone: 0049-431-71966-0, -30 Fax: 0049-431-71966-29 EMail: klammer@brockstedt.de
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-03-2619, VQE-05-7480
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 9" x 13", 13" x 20", 15" x 21", 18" x 24"
 Max. Number of Layers: 12
 Max. Board Thickness: .2"
 Min. Hole Size: .004" Laser Abated Plated Hole Size Before Plating, .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 1:1 Microvia, 7:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Hughes Circuits, Inc. 540 S. Pacific Street, San Marcos, CA, 92078-4056 US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 1KXU6 Phone: 760-744-0300 Fax: 760-744-6388 EMail: joe@hughescircuits.com</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-08-015865), VQE-12-24783
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 10
 Max. Board Thickness: .08"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 7:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Graphite-based
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: HASL

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-07-014018), VQE-12-24783
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 10
 Max. Board Thickness: .08"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 7:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Graphite-based
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: HASL

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: KCA Electronics, Inc. 223 N. Crescent Way, Anaheim, CA, 92801 US</p>		<p>CAGE Code: 1VUH8 Phone: 714-239-2433 Fax: 714-239-2455 EMail:</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-11-022964
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 10
 Max. Board Thickness: .0548"
 Min. Hole Size: .04" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 1.37:1 Through-Hole
 Min. Conductor Width/Space: .01"/.01"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: HASL
 Additional Fab Capabilities: Foil Lamination

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-11-021796
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Adhesiveless Polyimide
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 16
 Max. Board Thickness: .074"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 7:1 Through-Hole
 Min. Conductor Width/Space: .005"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: HASL
 Additional Fab Capabilities: Blind Vias, Foil Lamination, Sequential Lamination
 Flex Usage: Use A (Flex During Installation)

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3
 Qualification Letters: VQE-11-021796
 Flex Base Material: Copper Clad Polyimide with Acrylic Adhesive
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 1
 Max. Board Thickness: .008"
 Min. Conductor Width/Space: .004"/.006"
 Finish System: HASL
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION:

KCA Electronics, Inc.

223 N. Crescent Way, Anaheim, CA, 92801 US

CAGE Code: 1VUH8

Phone: 714-239-2433

Fax: 714-239-2455

E-Mail:

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2

Qualification Letters: VQE-11-022398

Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant

Max. Panel Size: 18" x 24"

Max. Number of Layers: 20

Max. Board Thickness: .092"

Min. Hole Size: .0079" Drilled Plated-Through Hole Before Plating

Aspect Ratio: 7:1 Through-Hole

Min. Conductor Width/Space: .0048"/.004"

Hole Preparation: Plasma Desmear

Hole Wall Conductive Coating: Electroless Copper

Copper Plating: Direct Current Plate

Hole Fill/Via Plug: Non-Conductive

Solder Resist: Dry Film, Liquid Photoimageable

Finish System: HASL

Additional Fab Capabilities: Buried Vias, Embedded Resistors, Foil Lamination, Sequential Lamination

Controlled Impedance: Differential, Single-Ended

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Lockheed Martin Mission Systems & Training 1801 State Route 17C, Owego, NY, 13827 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 03640 Phone: 607-751-5395 Fax: 607-751-7714 E-Mail: renee.akers@lmco.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-00-000961, VQE-99-000130
 Rigid Base Material: AF: Aramid Fabric, Woven, Majority Polyfunctional Epoxy Resin
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 16
 Max. Board Thickness: .2"
 Min. Hole Size: .02" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 8:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: Electrolytic Ni / Hard Au, HASL, Hot Oil Reflow of Plated Sn/Pb

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-01-0539
 Rigid Base Material: BI: Aramid Fabric, Nonwoven, Polyimide Resin
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 14
 Max. Board Thickness: .095"
 Min. Hole Size: .014" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 6.8:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: Electrolytic Ni / Hard Au, HASL, Hot Oil Reflow of Plated Sn/Pb

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-00-000961, VQE-07-013268, VQE-07-013459, VQE-11-022596, VQE-99-000130
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 24" x 30"
 Max. Number of Layers: 24
 Max. Board Thickness: .2"
 Min. Hole Size: .018" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 8:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: Electrolytic Ni / Hard Au, HASL, Hot Oil Reflow of Plated Sn/Pb

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Lockheed Martin Mission Systems & Training 1801 State Route 17C, Owego, NY, 13827 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 03640 Phone: 607-751-5395 Fax: 607-751-7714 E-Mail: renee.akers@lmco.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-00-000961, VQE-07-013459, VQE-99-000130
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 24" x 30"
 Max. Number of Layers: 16
 Max. Board Thickness: .2"
 Min. Hole Size: .018" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 8:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: Electrolytic Ni / Hard Au, HASL, Hot Oil Reflow of Plated Sn/Pb

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-00-000684, VQE-07-013459
 Composition: S - Homogenous thermosetting base material printed boards
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Adhesiveless Polyimide
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 18
 Max. Board Thickness: .11"
 Min. Hole Size: .016" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 6:1 Through-Hole
 Min. Conductor Width/Space: .003"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: HASL, Hot Oil Reflow of Plated Sn/Pb
 Flex Usage: Use A (Flex During Installation)

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-00-000684, VQE-07-013459
 Composition: S - Homogenous thermosetting base material printed boards
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Polyimide with Acrylic Adhesive
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 18
 Max. Board Thickness: .11"
 Min. Hole Size: .016" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 6:1 Through-Hole
 Min. Conductor Width/Space: .003"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: HASL, Hot Oil Reflow of Plated Sn/Pb
 Flex Usage: Use A (Flex During Installation)

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Micom Corp. 475 Old Highway 8 NW, New Brighton, MN, 55112 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 34076 Phone: 651-604-2625 Fax: 651-636-1352 E-Mail: kmoe@micomcircuits.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-02-002780, VQE-03-002980, VQE-12-023661
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 28
 Max. Board Thickness: .239"
 Min. Hole Size: .007" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 11:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Permanganate Etchback, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Buried Vias, Embedded Resistors, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-02-002780, VQE-03-002980, VQE-12-023661
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 28
 Max. Board Thickness: .239"
 Min. Hole Size: .007" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 11:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Permanganate Etchback, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Midwest Printed Circuit Services 1741 Circuit Drive, Round Lake Beach, IL, 60073 US</p>		<p>CAGE Code: 0YYS4 Phone: 847-740-4120 Fax: 847-740-4187 EMail:</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-13-025705
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 10
 Max. Board Thickness: .1"
 Min. Hole Size: .023" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 4:1 Through-Hole
 Min. Conductor Width/Space: .01"/.01"
 Hole Preparation: Permanganate Desmear, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-12-024841, VQE-12-025070, VQE-13-025727
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 12
 Max. Board Thickness: .1"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 9.3:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL
 Additional Fab Capabilities: Controlled Depth Mechanically Drilled Low Aspect Ratio Blind Vias, Foil Lamination
 Controlled Impedance: Differential

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

<p>MANUFACTURER INFORMATION: Pioneer Circuits, Inc. 3000 S. Shannon Street, Santa Ana, CA, 92704-6321 US</p>		<p>CAGE Code: 65723 Phone: 714-641-3132 Fax: 714-641-3120 EMail: Quality@pioneer-circuits.com</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-09-017323, VQE-09-017656
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 22
 Max. Board Thickness: .177"
 Min. Hole Size: .0135" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 11:1 Through-Hole
 Min. Conductor Width/Space: .0035"/.0035"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Periodic Reverse Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni/Au, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Buried Vias, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-09-017323, VQE-09-017656
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 20
 Max. Board Thickness: .275"
 Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 11:1 Through-Hole
 Min. Conductor Width/Space: .0035"/.0035"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Periodic Reverse Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni/Au, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Buried Vias, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-09-017323, VQE-09-017656, VQE-10-029651
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Flex Base Material: Copper Clad Adhesiveless Polyimide
 Max. Panel Size: 18" x 26"
 Max. Number of Layers: 22
 Max. Board Thickness: .231"
 Min. Hole Size: .02" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 8.5:1 Through-Hole
 Min. Conductor Width/Space: .003"/.003"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Periodic Reverse Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni/Au, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Buried Vias, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended
 Flex Usage: Use A (Flex During Installation)

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

<p>MANUFACTURER INFORMATION: Pioneer Circuits, Inc. 3000 S. Shannon Street, Santa Ana, CA, 92704-6321 US</p>		<p>CAGE Code: 65723 Phone: 714-641-3132 Fax: 714-641-3120 EMail: Quality@pioneer-circuits.com</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-09-017323, VQE-09-017656
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Polyimide with Acrylic Adhesive
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 10
 Max. Board Thickness: .1"
 Min. Hole Size: .016" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 6:1 Through-Hole
 Min. Conductor Width/Space: .0035"/.0035"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Periodic Reverse Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni/Au, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Book Binder, Buried Vias, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-09-017323, VQE-09-017656
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Adhesiveless Polyimide
 Max. Panel Size: 24" x 36"
 Max. Number of Layers: 26
 Max. Board Thickness: .185"
 Min. Hole Size: .013" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 11:1 Through-Hole
 Min. Conductor Width/Space: .0035"/.0035"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Periodic Reverse Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni/Au, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Book Binder, Buried Vias, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: PNC, Inc. 115 East Centre Street, Nutley, NJ, 07110 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 66766 Phone: 973-284-1600 Fax: EMail: carmela@pnconline.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
Qualification Letters: VQE-10-19440
Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
Max. Panel Size: 18" x 22"
Max. Number of Layers: 10
Max. Board Thickness: .093"
Min. Hole Size: .014" Drilled Plated-Through Hole Before Plating
Aspect Ratio: 6.6:1 Through-Hole
Min. Conductor Width/Space: .008"/.008"
Hole Preparation: Permanganate Desmear
Hole Wall Conductive Coating: Electroless Copper
Copper Plating: Direct Current Plate
Solder Resist: Liquid Photoimageable
Finish System: HASL
Additional Fab Capabilities: Foil Lamination

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Printed Circuits, Inc. 1200 West 96th Street, Bloomington, MN, 55431 US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 65114 Phone: 612-888-7900 Fax: 612-888-2719 EMail: jsmith@printedcircuits.com</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-01-000024
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Adhesiveless Polyimide
 Max. Panel Size: 12" x 18", 18" x 24"
 Max. Number of Layers: 16
 Max. Board Thickness: .12"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 10:1 Through-Hole
 Min. Conductor Width/Space: .004"/.005"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Pulse Plate
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Sequential Lamination
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Pro-Tech Interconnect Solutions LLC 4300 Peavey Road, Chaska, MN, 55318 US</p>		<p>CAGE Code: 3CP65 Phone: 952-442-2189 Fax: 952-442-2472 EMail: hkooda@protechmn.com</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-11-021704
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 12" x 24"
 Max. Number of Layers: 10
 Max. Board Thickness: .1"
 Min. Hole Size: .024" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 4:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: HASL

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-11-021704
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 10
 Max. Board Thickness: .1"
 Min. Hole Size: .024" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 4:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: HASL

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Sanmina-SCI (Costa Mesa) 2945 Airway Avenue, Costa Mesa, CA, 92626 US</p>		<p>CAGE Code: 3BKL5 Phone: 714-371-2800 Fax: 714-371-2833 EMail: joann.medina@sanmina-sci.com</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-12-024031
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 8
 Max. Board Thickness: .063"
 Min. Hole Size: .005" Laser Abated Plated Hole Size Before Plating, .013" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 1:1 Microvia, 5:1 Through-Hole
 Min. Conductor Width/Space: .003"/.003"
 Hole Preparation: Permanganate Desmear, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: Electrolytic Ni / Soft Au, HASL
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination, Press Fit Mounting, Sequential Lamination
 Controlled Impedance: Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-12-24471
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 18
 Max. Board Thickness: .093"
 Min. Hole Size: .013" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 7 : 1 Through-Hole
 Min. Conductor Width/Space: .003"/.0035"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: Electrolytic Ni / Soft Au, HASL
 Additional Fab Capabilities: Foil Lamination
 Controlled Impedance: Single-Ended

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Sanmina-SCI (Owego) 1200 Taylor Rd., Owego, NY, 13827 US</p>		<p>CAGE Code: 4GZ84 Phone: 607-689-5543 Fax: EMail: rick.sylvain@sanmina-sci.com</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-11-21597
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 12
 Max. Board Thickness: .11"
 Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 9.3:1 Through-Hole
 Min. Conductor Width/Space: .008"/.0045"
 Hole Preparation: Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Pulse Plate
 Solder Resist: Liquid Photoimageable
 Finish System: HASL
 Additional Fab Capabilities: Foil Lamination

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-11-22386
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 20
 Max. Board Thickness: .095"
 Min. Hole Size: .007" Laser Abated Plated Hole Size Before Plating, .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: .59:1 Microvia, 9.7:1 Through-Hole
 Min. Conductor Width/Space: .0035"/.0032"
 Hole Preparation: Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Pulse Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: HASL
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Sanmina-SCI (San Jose) 2050 Bering Drive, San Jose, CA, 95131 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 3DR67 Phone: 408-964-6515 Fax: 408-964-6453 E-Mail: darrell.myers@sanmina-sci.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-06-11137, VQE-10-19381, VQE-11-22038
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 21" x 27"
 Max. Number of Layers: 30
 Max. Board Thickness: .25"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 14:1 Through-Hole
 Min. Conductor Width/Space: .003"/.003"
 Hole Preparation: Plasma Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Pulse Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb, ImmAg, OSP
 Additional Fab Capabilities: Buried Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-06-11137
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 30
 Max. Board Thickness: .25"
 Min. Hole Size: .005" Laser Abated Plated Hole Size Before Plating, .008" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 15:1 Through-Hole, 1:2 Microvia
 Min. Conductor Width/Space: .003"/.003"
 Hole Preparation: Plasma Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Pulse Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/2, MIL-PRF-31032/6
 Qualification Letters: VQE-10-20921, VQE-10-21014
 Rigid Base Material: Woven Glass Reinforced, Hydrocarbon Resin with Ceramic Fill
 Max. Panel Size: 21" x 24"
 Max. Number of Layers: 2
 Max. Board Thickness: .062"
 Min. Hole Size: .0197" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 3.1:1 Through-Hole
 Min. Conductor Width/Space: .008"/.014"
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Pulse Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Sanmina-SCI (San Jose) 2050 Bering Drive, San Jose, CA, 95131 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 3DR67 Phone: 408-964-6515 Fax: 408-964-6453 EMail: darrell.myers@sanmina-sci.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/5
 Qualification Letters: VQE-11-021514
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; Woven Glass Reinforced, Hydrocarbon Resin with Ceramic Fill
 Max. Panel Size: 21" x 24"
 Max. Number of Layers: 7
 Max. Board Thickness: .066"
 Min. Hole Size: .01"
 Aspect Ratio: 7:1 Through-Hole
 Min. Conductor Width/Space: .005"/.004"
 Hole Preparation: Plasma Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Pulse Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG
 Additional Fab Capabilities: Blind Vias, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Speedy Circuits, Inc. 5331 McFadden Avenue, Huntington Beach, CA, 92649-1204 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 66982 Phone: 714-898-4901 Fax: 714-891-0607 E-Mail: sales@speedycircuits.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-08-016434, VQE-10-021007
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 14
 Max. Board Thickness: .11"
 Min. Hole Size: .015" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 7:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: Electrolytic Ni (no Au), HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Foil Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-08-016434, VQE-10-021007
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 14
 Max. Board Thickness: .11"
 Min. Hole Size: .015" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 7:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Foil Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-08-016434, VQE-10-019157, VQE-10-021007
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Adhesiveless Polyimide
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 18
 Max. Board Thickness: .13"
 Min. Hole Size: .002" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 7:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Foil Lamination
 Controlled Impedance: Differential, Single-Ended
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Speedy Circuits, Inc. 5331 McFadden Avenue, Huntington Beach, CA, 92649-1204 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 66982 Phone: 714-898-4901 Fax: 714-891-0607 E-Mail: sales@speedycircuits.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/6
 Qualification Letters: VQE-08-016434
 Composition: H - Homogenous thermoplastic base material printed boards
 Rigid Base Material: GR: Glass Base, Nonwoven, Polytetrafluoroethylene Resin, Flame Resistant; GY: Glass Base, Woven, Polytetrafluoroethylene Resin, Flame Resistant, for Microwave Application
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 2
 Max. Board Thickness: .036"
 Min. Hole Size: .02" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 2:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Finish System: Hot Oil Reflow of Plated Sn/Pb

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/5, MIL-PRF-31032/6
 Qualification Letters: VQE-09-018657
 Composition: M - Mixed based material printed boards
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; With or without woven or non-woven E-glass, Polytetrafluoroethylene (PTFE) resin, ceramic filler
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 10 Woven E-Glass, Hydrocarbon Resin, Ceramic Filler - Homogenous
 Max. Board Thickness: .1"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 10:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Plasma Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL, Hot Oil Reflow of Plated Sn/Pb
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/5, MIL-PRF-31032/6
 Qualification Letters: VQE-09-018657
 Composition: S - Homogenous thermosetting base material printed boards
 Rigid Base Material: Woven Glass Reinforced, Hydrocarbon Resin with Ceramic Fill
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 10 With or Without Woven or Non-woven E-Glass, PTFE Resin, Ceramic Filler and Woven E-Glass, Epoxy Resin - Mixed
 Max. Board Thickness: .068"
 Min. Hole Size: .01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 6:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Plasma Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL, Hot Oil Reflow of Plated Sn/Pb
 Controlled Impedance: Differential, Single-Ended

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

<p>MANUFACTURER INFORMATION: TTM Technologies (Santa Ana) 2630 South Harbor Boulevard, Santa Ana, CA, 92704 US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 1WQ42 Phone: 714-241-0303, x3127 Fax: 714-241-0708 EMail: tlichte@ttmtech.com</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-05-8644, VQE-06-011211
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 24
 Max. Board Thickness: .2"
 Min. Hole Size: .013" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 14:1 Through-Hole, 1:1 Microvia
 Min. Conductor Width/Space: .003"/.003"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb, ImmAg, OSP
 Additional Fab Capabilities: Blind Vias, Buried Vias, Sequential Lamination

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-05-8644, VQE-06-011211, VQE-12-023569
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 24
 Max. Board Thickness: .2"
 Min. Hole Size: .013" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 14:1 Through-Hole, 1:1 Microvia
 Min. Conductor Width/Space: .003"/.003"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb, ImmAg, OSP
 Additional Fab Capabilities: Blind Vias, Buried Vias, Sequential Lamination

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: TTM Technologies (Santa Clara) 407 Mathew Street, Santa Clara, CA, 95050 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 65916 Phone: 408-486-3184 Fax: 408-727-1003 EMail: nellie.gutierrez@ttmtech.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-03-003888, VQE-10-020500, VQE-10-020581, VQE-11-022973
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 20
 Max. Board Thickness: .12"
 Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 9:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Etchback, Plasma Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive
 Solder Resist: Liquid Photoimageable, Silk Screen
 Finish System: ENIG, Electrolytic Ni (no Au), Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL
 Additional Fab Capabilities: Blind Vias, Foil Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-03-003888, VQE-10-020500, VQE-10-020581, VQE-11-022973
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 12
 Max. Board Thickness: .12"
 Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 9:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive
 Solder Resist: Liquid Photoimageable, Silk Screen
 Finish System: ENIG, Electrolytic Ni (no Au), Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL
 Additional Fab Capabilities: Blind Vias, Foil Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-03-003895, VQE-10-020500, VQE-10-020581, VQE-11-022973
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Adhesiveless Polyimide
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 16
 Max. Board Thickness: .12"
 Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 9:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive
 Finish System: ENIG, Electrolytic Ni (no Au), Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL
 Additional Fab Capabilities: Sequential Lamination
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: TTM Technologies (Santa Clara) 407 Mathew Street, Santa Clara, CA, 95050 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 65916 Phone: 408-486-3184 Fax: 408-727-1003 EMail: nellie.gutierrez@ttmtech.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-03-003895, VQE-10-020500, VQE-10-020581, VQE-11-022973
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Polyimide with Acrylic Adhesive
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 10
 Max. Board Thickness: .1"
 Min. Hole Size: .031" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 3:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive
 Finish System: ENIG, Electrolytic Ni (no Au), Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-07-013211, VQE-11-022973
 Composition: H - Homogenous thermoplastic base material printed boards, M - Mixed based material printed boards
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; Woven Glass Reinforced, Hydrocarbon Resin with Ceramic Fill
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 6
 Max. Board Thickness: .062"
 Min. Hole Size: .015" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 4:1 Through-Hole
 Min. Conductor Width/Space: .007"/.008"
 Hole Preparation: Permanganate Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni (no Au), Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL
 Additional Fab Capabilities: Blind Vias
 Controlled Impedance: Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-03-003888, VQE-10-020500, VQE-10-020581, VQE-11-022973
 Rigid Base Material: BI: Aramid Fabric, Nonwoven, Polyimide Resin
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 11
 Max. Board Thickness: .12"
 Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 6.45:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive
 Solder Resist: Liquid Photoimageable, Silk Screen
 Finish System: ENIG, Electrolytic Ni (no Au), Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL
 Additional Fab Capabilities: Blind Vias
 Controlled Impedance: Differential, Single-Ended

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: TTM Technologies (Stafford) 4 Old Monson Road, Stafford, CT, 77497 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 5L706 Phone: 860-684-5881 Fax: 860-684-7425 E-Mail: michele.hebert@ttmtech.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-03-003348, VQE-09-018855, VQE-11-023287, VQE-12-023366
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; Woven E-Glass, Epoxy Resin, Flame Resistant, with Inorganic Filler
 Max. Panel Size: 30" x 54"
 Max. Number of Layers: 50
 Max. Board Thickness: .4"
 Min. Hole Size: .0079" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 14:1 Through-Hole, 1:1 Microvia
 Min. Conductor Width/Space: .004"/.003"
 Hole Preparation: Permanganate Etchback, Plasma Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable, Silk Screen
 Finish System: ENIG, Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL, Hot Oil Reflow of Plated Sn/Pb, Ni/Pd/Au
 Additional Fab Capabilities: Blind Vias, Buried Vias, Copper Core, Copper Invar Copper, Embedded Resistors, Press Fit Mounting, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-03-003348, VQE-09-018855, VQE-11-023287, VQE-12-023366
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 32
 Max. Board Thickness: .13"
 Min. Hole Size: 11.8" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 11:1 Through-Hole, 1:1 Microvia
 Min. Conductor Width/Space: .004"/.003"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable, Silk Screen
 Finish System: ENIG, Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL, Hot Oil Reflow of Plated Sn/Pb, Ni/Pd/Au
 Additional Fab Capabilities: Blind Vias, Buried Vias, Copper Core, Copper Invar Copper, Embedded Resistors, Press Fit Mounting, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-03-003348, VQE-09-018855, VQE-11-023287
 Rigid Base Material: AF: Aramid Fabric, Woven, Majority Polyfunctional Epoxy Resin
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 10
 Max. Board Thickness: .1"
 Min. Hole Size: .032" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 1:1 Microvia, 3:1 Through-Hole
 Min. Conductor Width/Space: .004"/.003"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable, Silk Screen
 Finish System: ENIG, Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL, Hot Oil Reflow of Plated Sn/Pb, Ni/Pd/Au
 Additional Fab Capabilities: Blind Vias, Buried Vias, Sequential Lamination,
 Controlled Impedance: Differential, Single-Ended

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: TTM Technologies (Stafford) 4 Old Monson Road, Stafford, CT, 77497 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 5L706 Phone: 860-684-5881 Fax: 860-684-7425 E-Mail: michele.hebert@ttmtech.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-03-003348, VQE-09-018855, VQE-11-023287, VQE-12-023366
 Rigid Base Material: BI: Aramid Fabric, Nonwoven, Polyimide Resin
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 10
 Max. Board Thickness: .1"
 Min. Hole Size: .0118" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 1:1 Microvia, 6:1 Through-Hole
 Min. Conductor Width/Space: .004"/.003"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable, Silk Screen
 Finish System: ENIG, Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL, Hot Oil Reflow of Plated Sn/Pb, Ni/Pd/Au
 Additional Fab Capabilities: Blind Vias, Buried Vias, Sequential Lamination,
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-03-003348, VQE-09-018855, VQE-11-023287
 Rigid Base Material: GM: Glass Base, Woven, Triazine and/or Bismaleimide Modified Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 10
 Max. Board Thickness: .1"
 Min. Hole Size: .032" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 1:1 Microvia, 3:1 Through-Hole
 Min. Conductor Width/Space: .004"/.003"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable, Silk Screen
 Finish System: ENIG, Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL, Hot Oil Reflow of Plated Sn/Pb, Ni/Pd/Au
 Additional Fab Capabilities: Blind Vias, Buried Vias, Sequential Lamination,
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: Custom
 Qualification Letters: VQE-03-003348, VQE-10-019855, VQE-11-023287
 Rigid Base Material: With or without woven or non-woven E-glass, Polytetrafluoroethylene (PTFE) resin, ceramic filler
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 12
 Max. Board Thickness: .11"
 Min. Hole Size: .0197" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 3.3:1 Through-Hole
 Min. Conductor Width/Space: .006"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable, Silk Screen
 Finish System: ENIG, Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL, Hot Oil Reflow of Plated Sn/Pb, Ni/Pd/Au
 Additional Fab Capabilities: Embedded Resistors
 Controlled Impedance: Differential, Single-Ended

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: TTM Technologies (Stafford) 4 Old Monson Road, Stafford, CT, 77497 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 5L706 Phone: 860-684-5881 Fax: 860-684-7425 E-Mail: michele.hebert@ttmtech.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: Custom
 Qualification Letters: VQE-03-003348, VQE-10-019855, VQE-11-023287
 Composition: M - Mixed based material printed boards
 Rigid Base Material: Woven Glass Reinforced, Hydrocarbon Resin with Ceramic Fill
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 24
 Max. Board Thickness: .175"
 Min. Hole Size: .0177" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 9:1 Through-Hole
 Min. Conductor Width/Space: .006"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable, Silk Screen
 Finish System: ENIG, Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL, Hot Oil Reflow of Plated Sn/Pb, Ni/Pd/Au
 Additional Fab Capabilities: Buried Vias, Embedded Resistors
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-03-003349, VQE-09-018855, VQE-10-019456, VQE-11-023287, VQE-12-023366
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant; Woven E-Glass, Epoxy Resin, Flame Resistant, with Inorganic Filler
 Flex Base Material: Copper Clad Adhesiveless Polyimide
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 24
 Max. Board Thickness: .125"
 Min. Hole Size: .013" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 1:1 Microvia, 9:1 Through-Hole
 Min. Conductor Width/Space: .004"/.003"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable, Silk Screen
 Finish System: ENIG, Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL, Hot Oil Reflow of Plated Sn/Pb, Ni/Pd/Au
 Additional Fab Capabilities: Blind Vias, Buried Vias, Copper Core, Sequential Lamination
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: TTM Technologies (Stafford) 4 Old Monson Road, Stafford, CT, 77497 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 5L706 Phone: 860-684-5881 Fax: 860-684-7425 E-Mail: michele.hebert@ttmtech.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-03-003349, VQE-10-019456, VQE-11-023287
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant; Woven E-Glass, Epoxy Resin, Flame Resistant, with Inorganic Filler
 Flex Base Material: Copper Clad Polyimide with Acrylic Adhesive
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 11
 Max. Board Thickness: .07"
 Min. Hole Size: .35" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 1:1 Microvia, 2:1 Through-Hole
 Min. Conductor Width/Space: .004"/.003"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable, Silk Screen
 Finish System: ENIG, Electrolytic Ni / Hard Au, Electrolytic Ni / Soft Au, HASL, Hot Oil Reflow of Plated Sn/Pb, Ni/Pd/Au
 Additional Fab Capabilities: Blind Vias, Buried Vias, Sequential Lamination,
 Controlled Impedance: Differential, Single-Ended
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Unicircuit, Inc. 8192 Southpark Lane, Littleton, CO, 80120 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 66311 Phone: 303-730-0505, x110 Fax: EMail: blageman@unicircuit.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-07-13789, VQE-09-17422, VQE-11-23044
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 16
 Max. Board Thickness: .12"
 Min. Hole Size: .006" Laser Abated Plated Hole Size Before Plating, .02" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 6:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Pulse Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-09-17422, VQE-12-24296
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 20" x 26"
 Max. Number of Layers: 16
 Max. Board Thickness: .12"
 Min. Hole Size: .008" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 15:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Pulse Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: HASL, Hot Oil Reflow of Plated Sn/Pb
 Controlled Impedance: Differential, Single-Ended

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Vermont Circuits, Inc. 76 Technology Drive, Brattleboro, VT, 05302-1890 US</p>		<p>CAGE Code: 65200 Phone: Fax: EMail:</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-10-019275, VQE-11-022979
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24", 18" x 24"
 Max. Number of Layers: 12
 Max. Board Thickness: .1"
 Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 7.5:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Permanganate Desmear, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL
 Additional Fab Capabilities: Foil Lamination
 Controlled Impedance: Differential

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Viasystems Cleveland Inc. 7 Ascot Parkway, Cuyahoga Falls, OH, 44223 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 7Z463 Phone: 330-572-3400 Fax: 330-572-3434 EMail:
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-00-000289, VQE-01-000910, VQE-05-008414, VQE-06-010963
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 10
 Max. Board Thickness: .126"
 Min. Hole Size: .015" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 5:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-00-000289, VQE-01-000910, VQE-05-008414, VQE-06-010963
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 16
 Max. Board Thickness: .126"
 Min. Hole Size: .013" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 5:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-01-000909, VQE-06-010963
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Polyimide with Acrylic Adhesive
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 7
 Max. Board Thickness: .07"
 Min. Hole Size: .026" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 2.6:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Finish System: HASL
 Flex Usage: Use A (Flex During Installation)

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Viasystems Cleveland Inc. 7 Ascot Parkway, Cuyahoga Falls, OH, 44223 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 7Z463 Phone: 330-572-3400 Fax: 330-572-3434 EMail:
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-01-000909, VQE-06-010963
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Adhesiveless Polyimide
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 11
 Max. Board Thickness: .126"
 Min. Hole Size: .013" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 10:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Finish System: HASL
 Flex Usage: Use A (Flex During Installation)

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Viasystems Corporation (CA) 355 Turtle Creek Court, San Jose, CA, 95125-1316 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 0MHG5 Phone: 408-938-7219 Fax: 408-280-0641 E-Mail: arnold.amaral@viasystems.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-08-016481), VQ(VQE-08-016632)
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 20
 Max. Board Thickness: .13"
 Min. Hole Size: .004" Laser Abated Plated Hole Size Before Plating, .008" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 0.8:1 Microvia, 10:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Pulse Plate
 Hole Fill/Via Plug: Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni, Electrolytic Ni / Hard Au, HASL
 Additional Fab Capabilities: Blind Vias, Buried Vias, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-08-016481), VQ(VQE-08-016632)
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 20
 Max. Board Thickness: .13"
 Min. Hole Size: .008" Drilled Plated-Through Hole Before Plating, .008" Laser Abated Plated Hole Size Before Plating
 Aspect Ratio: 0.8:1 Microvia, 10:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate, Pulse Plate
 Hole Fill/Via Plug: Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL
 Additional Fab Capabilities: Blind Vias, Buried Vias, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Viasystems Corporation (OR) 1521 Poplar Lane, Forest Grove, OR, 97116 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 01KV9 Phone: (503) 992-4068 Fax: EMail: dennis.hammer@viasystems.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-10-019896)
 Composition: M - Mixed based material printed boards
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; Woven Glass Reinforced, Hydrocarbon Resin with Ceramic Fill
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 6
 Max. Board Thickness: .062"
 Min. Hole Size: .016" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 4:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL, ImmAg
 Additional Fab Capabilities: Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-09-017325), VQ(VQE-09-018901), VQ(VQE-10-019896)
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 26
 Max. Board Thickness: .13"
 Min. Hole Size: .003" Laser Abated Plated Hole Size Before Plating, .008" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 0.8:1 Microvia, 10:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL, ImmAg
 Additional Fab Capabilities: Blind Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-09-017325), VQ(VQE-09-018901), VQ(VQE-10-019896)
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 26
 Max. Board Thickness: .13"
 Min. Hole Size: .003" Laser Abated Plated Hole Size Before Plating, .008" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 0.8:1 Microvia, 10:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni / Hard Au, HASL, ImmAg
 Additional Fab Capabilities: Blind Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Viasystems Denver Inc. 10570 Bradford Road, Littleton, CO, 80127 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 75815 Phone: 303-972-4105 Fax: 303-933-2934 E-Mail:
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-02-000317, VQE-05-007627, VQE-05-009014, VQE-09-018719, VQE-10-020224, VQE-12-024984, VQE-13-026251, VQE-13-026429
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 24
 Max. Board Thickness: .125"
 Min. Hole Size: .005" Laser Abated Plated Hole Size Before Plating, .0118" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 10:1 Through-Hole, 1:1 Microvia
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-02-000317, VQE-05-007627, VQE-05-009014, VQE-09-018719, VQE-10-020224, VQE-12-024984, VQE-13-026251, VQE-13-026429
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 20
 Max. Board Thickness: .125"
 Min. Hole Size: .005" Laser Abated Plated Hole Size Before Plating, .0118" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 10:1 Through-Hole, 1:1 Microvia
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Permanganate Desmear, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Viasystems Milpitas, Inc. 1992 Tarob Court, Milpitas, CA, 95035</p>		<p>CAGE Code: 0SFV5 Phone: 408-263-0940 Fax: 408-263-9115 EMail:</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-12-024360
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18.5" x 24.5"
 Max. Number of Layers: 22
 Max. Board Thickness: .115"
 Min. Hole Size: .009" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 10:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-12-024360
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18.5" x 24.5"
 Max. Number of Layers: 22
 Max. Board Thickness: .115"
 Min. Hole Size: .009" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 10:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL
 Controlled Impedance: Differential, Single-Ended

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Viasystems North America Operations, Inc. - Anaheim 1220 N. Simon Circle, Anaheim, CA, 92806 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 0BSG1 Phone: 714-688-7296 Fax: EMail:
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-09-018147)
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 10
 Max. Board Thickness: .1"
 Min. Hole Size: .32" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 3:1 Through-Hole
 Min. Conductor Width/Space: .01"/.01"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL
 Additional Fab Capabilities: Foil Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-09-018147)
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 22
 Max. Board Thickness: .115"
 Min. Hole Size: .009" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 10:1 Through-Hole
 Min. Conductor Width/Space: .004"/.006"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination
 Controlled Impedance: Differential, Single-Ended

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Viasystems North America Operations, Inc. - Sterling 1200 Severn Way, Dulles, VA, 20166-8904 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 0K703 Phone: 703-652-2200 Fax: 703-652-2272 EMail:
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-03-003545), VQ(VQE-09-018207)
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 22
 Max. Board Thickness: .1"
 Min. Hole Size: .005" Laser Abated Plated Hole Size Before Plating, .009" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 10:1 Through-Hole
 Min. Conductor Width/Space: .004"/.003"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL
 Additional Fab Capabilities: Blind Vias, Buried Vias, Resistors
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-03-003545), VQ(VQE-09-018207)
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 22
 Max. Board Thickness: .1"
 Min. Hole Size: .005" Laser Abated Plated Hole Size Before Plating, .009" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 10:1 Through-Hole
 Min. Conductor Width/Space: .004"/.003"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL
 Additional Fab Capabilities: Blind Vias, Buried Vias, Resistors
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-11-021244)
 Rigid Base Material: Woven glass, reinforced, hydrocarbon resin, with ceramic fill
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 2
 Max. Board Thickness: .034"
 Min. Hole Size: .02" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 1.6:1 Through-Hole
 Min. Conductor Width/Space: .015"/.005"
 Hole Preparation: Plasma Desmear
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Viasystems North Jackson Inc. 12080 DeBartolo Drive, North Jackson, OH, 44451 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 0GN71 Phone: 330-538-3900 Fax: 330-538-3820 E-Mail:
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-03-003121), VQ(VQE-03-003214), VQ(VQE-07-012925), VQ(VQE-10-020405)
 Rigid Base Material: Bl: Aramid Fabric, Nonwoven, Polyimide Resin
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 24
 Max. Board Thickness: .25"
 Min. Hole Size: .008" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 15:1 Through-Hole
 Min. Conductor Width/Space: .003"/.003"
 Hole Preparation: Permanganate Desmear, Permanganate Etchback, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni/Au, HASL, ImmAg, Ni/Pd/Au, OSP
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-03-003121), VQ(VQE-03-003214), VQ(VQE-07-012925), VQ(VQE-10-020405)
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 24
 Max. Board Thickness: .25"
 Min. Hole Size: .008" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 15:1 Through-Hole
 Min. Conductor Width/Space: .003"/.003"
 Hole Preparation: Permanganate Desmear, Permanganate Etchback, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni/Au, HASL, ImmAg, Ni/Pd/Au, OSP
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQ(VQE-03-003121), VQ(VQE-03-003214), VQ(VQE-07-012925), VQ(VQE-10-020405)
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 24
 Max. Board Thickness: .25"
 Min. Hole Size: .008" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 15:1 Through-Hole
 Min. Conductor Width/Space: .003"/.003"
 Hole Preparation: Permanganate Desmear, Permanganate Etchback, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: ENIG, HASL, ImmAg, Ni/Pd/Au, OSP
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination
 Controlled Impedance: Differential, Single-Ended

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Viasystems North Jackson Inc. 12080 DeBartolo Drive, North Jackson, OH, 44451 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 0GN71 Phone: 330-538-3900 Fax: 330-538-3820 EMail:
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQ(VQE-03-003121), VQ(VQE-03-003214), VQ(VQE-07-012925), VQ(VQE-10-020405)
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Adhesiveless Polyimide
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 24
 Max. Board Thickness: .25"
 Min. Hole Size: .008" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 15:1 Through-Hole
 Min. Conductor Width/Space: .003"/.003"
 Hole Preparation: Permanganate Desmear, Permanganate Etchback, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni/Au, HASL, ImmAg, OSP
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQ(VQE-03-003121), VQ(VQE-03-003214), VQ(VQE-07-012925), VQ(VQE-10-020405)
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Polyimide with Acrylic Adhesive
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 24
 Max. Board Thickness: .25"
 Min. Hole Size: .008" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 15:1 Through-Hole
 Min. Conductor Width/Space: .003"/.003"
 Hole Preparation: Permanganate Desmear, Permanganate Etchback, Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Non-Conductive
 Solder Resist: Dry Film, Liquid Photoimageable
 Finish System: ENIG, Electrolytic Ni/Au, HASL, ImmAg, OSP
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination
 Controlled Impedance: Differential, Single-Ended

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Viasystems Toronto Inc. 8150 Sheppard Avenue East, Scarborough, Ontario Canada M1B 5K2	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 3AF82 Phone: 416-208-2100 Fax: 416-208-2196 E-Mail:
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-04-006240, VQE-08-015407, VQE-09-018857, VQE-11-022676, VQE-12-023550
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 18
 Max. Board Thickness: .088"
 Min. Hole Size: .0098" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 1:1 Microvia, 8.4:1 Through-Hole
 Min. Conductor Width/Space: .0037"/.0028"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper,
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL, ImmAg, Ni/Pd/Au
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-04-006240, VQE-08-015407, VQE-09-018857, VQE-11-022676, VQE-12-023550
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 20
 Max. Board Thickness: .093"
 Min. Hole Size: .0091" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 1:1 Microvia, 9.6:1 Through-Hole
 Min. Conductor Width/Space: .004"/.003"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Hole Fill/Via Plug: Conductive, Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL, ImmAg, Ni/Pd/Au
 Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination, Sequential Lamination
 Controlled Impedance: Differential, Single-Ended

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Westak of Oregon 3941 24th Avenue, Forest Grove, OR, 97116-2208	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 65745 Phone: 503-359-3593 Fax: 503-357-5332 E-Mail: or-qa@westak.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-13-026434
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 10
 Max. Board Thickness: .11"
 Min. Hole Size: .02" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 5.5:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL
 Controlled Impedance: Differential, Single-Ended

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-13-026434
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 10
 Max. Board Thickness: .11"
 Min. Hole Size: .02" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 5.5:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Permanganate Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL
 Controlled Impedance: Differential, Single-Ended

SECTION II
LIST OF MANUFACTURERS AND ASSOCIATED SPECIFICATION

AC Universal Circuits LLC MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
8860 Zachary Lane North, Maple Grove, MN, 55369-4524 US MIL-PRF-31032/2 MIL-PRF-31032/5
CAGE Code: 45032 MIL-PRF-31032/3 MIL-PRF-31032/6

Accurate Circuit Engineering MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
3019 S. Kilson Drive, Santa Ana, CA, 92707 US MIL-PRF-31032/2 MIL-PRF-31032/5
CAGE Code: 0MNN9 MIL-PRF-31032/3 MIL-PRF-31032/6

Advanced Circuits - Tempe Division MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
229 S. Clark Drive, Tempe, AZ, 85281-3073 MIL-PRF-31032/2 MIL-PRF-31032/5
CAGE Code: 6RJS1 MIL-PRF-31032/3 MIL-PRF-31032/6

Airborn Flexible Circuits, Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
11 Dohme Avenue, Toronto, Ontario Canada M4B 1Y7 MIL-PRF-31032/2 MIL-PRF-31032/5
CAGE Code: 38661 MIL-PRF-31032/3 MIL-PRF-31032/6

American Standard Circuits MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
475 Industrial Drive, West Chicago, IL, 60185 US MIL-PRF-31032/2 MIL-PRF-31032/5
CAGE Code: 4AA34 MIL-PRF-31032/3 MIL-PRF-31032/6

Amphenol Printed Circuits MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
91 Northeastern Boulevard, Nashua, NH, 03062 US MIL-PRF-31032/2 MIL-PRF-31032/5
CAGE Code: 57034 MIL-PRF-31032/3 MIL-PRF-31032/6

Calumet Electronics Corp. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
25830 Depot Street, Calumet, MI, 49913-1985 US MIL-PRF-31032/2 MIL-PRF-31032/5
CAGE Code: 65337 MIL-PRF-31032/3 MIL-PRF-31032/6

Cirexx International, Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
791 Nuttman Street, Santa Clara, CA, 95054 US MIL-PRF-31032/2 MIL-PRF-31032/5
CAGE Code: 4MEG7 MIL-PRF-31032/3 MIL-PRF-31032/6

Colonial Circuits, Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
1026 Warrenton Road, Fredericksburg, VA, 22406-6200 US MIL-PRF-31032/2 MIL-PRF-31032/5
CAGE Code: 6T499 MIL-PRF-31032/3 MIL-PRF-31032/6

Compunetics Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
700 Seco Rd, Monroeville, OH, 15146 MIL-PRF-31032/2 MIL-PRF-31032/5
CAGE Code: 30598 MIL-PRF-31032/3 MIL-PRF-31032/6

Cosmotronic, Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
16721 Noyes Avenue, Irvine, CA, 92606 US MIL-PRF-31032/2 MIL-PRF-31032/5
CAGE Code: 63695 MIL-PRF-31032/3 MIL-PRF-31032/6

Dynamic & Proto Circuits, Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
869 Barton Street, Stoney Creek, Ontario Canada L8E 5G6 MIL-PRF-31032/2 MIL-PRF-31032/5
CAGE Code: 38898 MIL-PRF-31032/3 MIL-PRF-31032/6

Electro Plate Circuitry, Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
1430 Century Drive, Carrollton, TX, 75006 US MIL-PRF-31032/2 MIL-PRF-31032/5
CAGE Code: 79616 MIL-PRF-31032/3 MIL-PRF-31032/6

Electrotek Corp. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
7745 S. 10th Street, Oak Creek, WI, 53154 US MIL-PRF-31032/2 MIL-PRF-31032/5
CAGE Code: 66030 MIL-PRF-31032/3 MIL-PRF-31032/6

SECTION II
LIST OF MANUFACTURERS AND ASSOCIATED SPECIFICATION

Endicott Interconnect Technologies, Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 Dept. 0069/014-3, 1093 Clark Street, Endicott, NY, 13760 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 3ECL3 MIL-PRF-31032/3 MIL-PRF-31032/6

Firan Technology Group MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 250 Finchdene Square, Scarborough, Ontario Canada M1X 1A5 MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: L2665 MIL-PRF-31032/3 MIL-PRF-31032/6

Global Innovations Corp. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 901 Hensley Drive, Wylie, TX, 75098 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 04RV5 MIL-PRF-31032/3 MIL-PRF-31032/6

Gorilla Circuits MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 1445 Old Oakland Rd, San Jose, CA, 95112 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 3C7D2 MIL-PRF-31032/3 MIL-PRF-31032/6

Graphic Plc MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 , Lords Meadow Industrial Estate, Down End, Crediton, Devon, EX17 IHN MIL-PRF-31032/2 MIL-PRF-31032/5
 United Kingdom MIL-PRF-31032/3 MIL-PRF-31032/6
 CAGE Code: U4538

Hamby Corporation MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 27704 Avenue Scott, Valencia, CA, 91355 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 07284 MIL-PRF-31032/3 MIL-PRF-31032/6

Hans Brockstedt GmbH MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 Clara-Immerwahr Strasse 7, 24145 Kiel Germany MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: C4831 MIL-PRF-31032/3 MIL-PRF-31032/6

Hughes Circuits, Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 540 S. Pacific Street, San Marcos, CA, 92078-4056 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 1KXU6 MIL-PRF-31032/3 MIL-PRF-31032/6

KCA Electronics, Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 223 N. Crescent Way, Anaheim, CA, 92801 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 1VUH8 MIL-PRF-31032/3 MIL-PRF-31032/6

Lockheed Martin Mission Systems & Training MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 1801 State Route 17C, Owego, NY, 13827 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 03640 MIL-PRF-31032/3 MIL-PRF-31032/6

Micom Corp. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 475 Old Highway 8 NW, New Brighton, MN, 55112 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 34076 MIL-PRF-31032/3 MIL-PRF-31032/6

Midwest Printed Circuit Services MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 1741 Circuit Drive, Round Lake Beach, IL, 60073 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 0YYS4 MIL-PRF-31032/3 MIL-PRF-31032/6

Pioneer Circuits, Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 3000 S. Shannon Street, Santa Ana, CA, 92704-6321 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 65723 MIL-PRF-31032/3 MIL-PRF-31032/6

PNC, Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 115 East Centre Street, Nutley, NJ, 07110 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 66766 MIL-PRF-31032/3 MIL-PRF-31032/6

SECTION II
LIST OF MANUFACTURERS AND ASSOCIATED SPECIFICATION

Printed Circuits, Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 1200 West 96th Street, Bloomington, MN, 55431 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 65114 MIL-PRF-31032/3 MIL-PRF-31032/6

Pro-Tech Interconnect Solutions LLC MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 4300 Peavey Road, Chaska, MN, 55318 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 3CP65 MIL-PRF-31032/3 MIL-PRF-31032/6

Sanmina-SCI (Costa Mesa) MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 2945 Airway Avenue, Costa Mesa, CA, 92626 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 3BKL5 MIL-PRF-31032/3 MIL-PRF-31032/6

Sanmina-SCI (Owego) MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 1200 Taylor Rd., Owego, NY, 13827 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 4GZ84 MIL-PRF-31032/3 MIL-PRF-31032/6

Sanmina-SCI (San Jose) MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 2050 Bering Drive, San Jose, CA, 95131 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 3DR67 MIL-PRF-31032/3 MIL-PRF-31032/6

Speedy Circuits, Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 5331 McFadden Avenue, Huntington Beach, CA, 92649-1204 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 66982 MIL-PRF-31032/3 MIL-PRF-31032/6

TTM Technologies (Santa Ana) MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 2630 South Harbor Boulevard, Santa Ana, CA, 92704 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 1WQ42 MIL-PRF-31032/3 MIL-PRF-31032/6

TTM Technologies (Santa Clara) MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 407 Mathew Street, Santa Clara, CA, 95050 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 65916 MIL-PRF-31032/3 MIL-PRF-31032/6

TTM Technologies (Stafford) MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 4 Old Monson Road, Stafford, CT, 77497 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 5L706 MIL-PRF-31032/3 MIL-PRF-31032/6

Unicircuit, Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 8192 Southpark Lane, Littleton, CO, 80120 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 66311 MIL-PRF-31032/3 MIL-PRF-31032/6

Vermont Circuits, Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 76 Technology Drive, Brattleboro, VT, 05302-1890 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 65200 MIL-PRF-31032/3 MIL-PRF-31032/6

Viasystems Cleveland Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 7 Ascot Parkway, Cuyahoga Falls, OH, 44223 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 7Z463 MIL-PRF-31032/3 MIL-PRF-31032/6

Viasystems Corporation (CA) MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 355 Turtle Creek Court, San Jose, CA, 95125-1316 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 0MHG5 MIL-PRF-31032/3 MIL-PRF-31032/6

Viasystems Corporation (OR) MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 1521 Poplar Lane, Forest Grove, OR, 97116 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 01KV9 MIL-PRF-31032/3 MIL-PRF-31032/6

SECTION II
LIST OF MANUFACTURERS AND ASSOCIATED SPECIFICATION

Viasystems Denver Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 10570 Bradford Road, Littleton, CO, 80127 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 75815 MIL-PRF-31032/3 MIL-PRF-31032/6

Viasystems Milpitas, Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 1992 Tarob Court, Milpitas, CA, 95035 MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 0SFV5 MIL-PRF-31032/3 MIL-PRF-31032/6

Viasystems North America Operations, Inc. - Anaheim MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 1220 N. Simon Circle, Anaheim, CA, 92806 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 0BSG1 MIL-PRF-31032/3 MIL-PRF-31032/6

Viasystems North America Operations, Inc. - Sterling MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 1200 Severn Way, Dulles, VA, 20166-8904 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 0K703 MIL-PRF-31032/3 MIL-PRF-31032/6

Viasystems North Jackson Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 12080 DeBartolo Drive, North Jackson, OH, 44451 US MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 0GN71 MIL-PRF-31032/3 MIL-PRF-31032/6

Viasystems Toronto Inc. MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 8150 Sheppard Avenue East, Scarborough, Ontario Canada M1B 5K2 MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 3AF82 MIL-PRF-31032/3 MIL-PRF-31032/6

Westak of Oregon MIL-PRF-31032/1 MIL-PRF-31032/4 Custom
 3941 24th Avenue, Forest Grove, OR, 97116-2208 MIL-PRF-31032/2 MIL-PRF-31032/5
 CAGE Code: 65745 MIL-PRF-31032/3 MIL-PRF-31032/6